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ABSTRACT OF THE DISCLOSURE

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A method of making a microelectronic assembly includes providing a first microelectronic element having one or more conductive bumps, the conductive bumps including a first fusible material that transforms from a solid to a liquid at a first melting temperature, and providing a second microelectronic element having one or more conductive elements. The conductive bumps of the first microelectronic element are electrically interconnected with the conductive elements of the second microelectronic element using a second fusible material, the second fusible material having a second melting temperature that is lower than the first melting temperature of the first fusible material. During the electrically interconnecting step, the second fusible material is maintained at a temperature that is greater than or equal to the second melting temperature and less than the first melting temperature of the first fusible material.

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